UMW FDN352AP

-30V P-Channel MOSFET

1.Description

These devices are well suited for low voltage and battery pow-ered applications where low in-line power loss is needed in a very small outline surface mount package.

2.Features

- $V_{DS(V)}$=-30V
- I_D(V_{GS}=-10V)=-1.3A
- $R_{DS(ON)}$(V_{GS}=-10V)≤180mΩ
- $R_{DS(ON)}$(V_{GS}=-4.5V)≤300mΩ

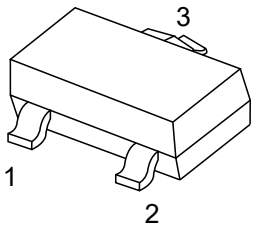
3.Application

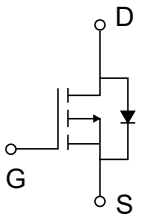
- Notebook computer power management

4.Pinning information

Pin	Symbol	Description
1	G	GATE
2	S	SOURCE
3	D	DRAIN

SOT-23





5.Maximum ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	-30	V
Gate-Source Voltage	V_{GSS}	±25	V
Drain Current – Continuous (Note 1a)	I_D	-1.3	A
– Pulsed		-10	
Maximum Power Dissipation(Note 1a)	P_D	0.5	W
(Note 1b)		0.46	
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	°C
Thermal Characteristics			
Thermal Resistance, Junction-to-Ambient (Note 1a)	$R_{\theta JA}$	250	°C/W
Thermal Resistance, Junction-to-Case (Note 1)	$R_{\theta JC}$	75	°C/W

6.T_A=25°C unless otherwise specified

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	I_D=-250μA, V_{GS}=0V	-30			V
Breakdown Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	I_D=-250μA Referenced to 25°C		-17		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-24V, V_{GS}=0V			-1	μA
Gate–Body Leakage	I_{GSS}	V_{GS}=±25V, V_{DS}=0V			±100	nA
On Characteristics (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-250μA	-0.8	-2	-2.5	V
Gate Threshold Voltage Temperature Coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	I_D=-250μA Referenced to 25°C		4		mV/°C
Static Drain–Source On–Resistance	$R_{DS(ON)}$	V_{GS}=-10V, I_D=-1.3A		150	180	mΩ
		V_{GS}=-4.5V, I_D=-1.1A		250	300	mΩ
Forward Transconductance	g_{FS}	V_{DS}=-5V, I_D=-0.9A		2		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS}=-15V, V_{GS}=0V,f =1MHz		150		pF
Output Capacitance	C_{oss}			40		pF
Reverse Transfer Capacitance	C_{rss}			20		pF
SWITCHING PARAMETERS (Note 2)						
Turn-On DelayTime	$t_{D(on)}$	V_{DD}=-10V, I_D=-1A V_{GS}=-10V, R_{GEN}=6Ω		4	8	ns
Turn-On Rise Time	t_r			15	28	ns
Turn-Off DelayTime	$t_{D(off)}$			10	18	ns
Turn-Off Fall Time	t_f			1	2	ns
Total Gate Charge	Q_g	V_{DS}=-10V, I_D=-0.9A V_{GS}=-4.5V		1.4	1.9	nC
Gate–Source Charge	Q_{gs}			0.5		nC
Gate–Drain Charge	Q_{gd}			0.5		nC

Drain–Source Diode Characteristics and Maximum Ratings						
Maximum Continuous Drain–Source Diode Forward Current	I_S				-0.42	A
Drain–Source Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=-0.42A (Note 2)		-0.8	-1.2	V
Diode Reverse Recovery Time	t_{rr}	I_F=-3.9A		17		ns
Diode Reverse Recovery Charge	Q_{rr}	dI_F/dt=100A/μs		7		nC

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface ofthe drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.

(a) $R_{\theta JA}$ = 250°C/W when mounted on a 0.02 in^2 pad of 2oz. copper.

(b) $R_{\theta JA}$ = 270°C/W when mounted on a 0.001 in^2 pad of 2oz. copper.

2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

7.1Typical Characterisitics

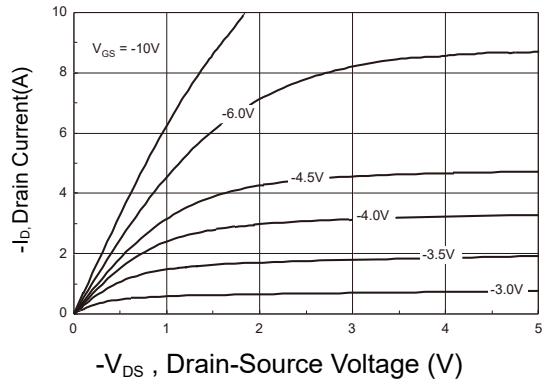


Figure 1: On-Region Characteristics.

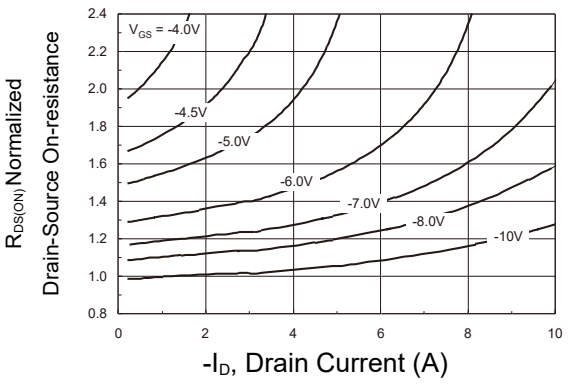


Figure 2: On-Resistance Variation with Drain Current and Gate Voltage.

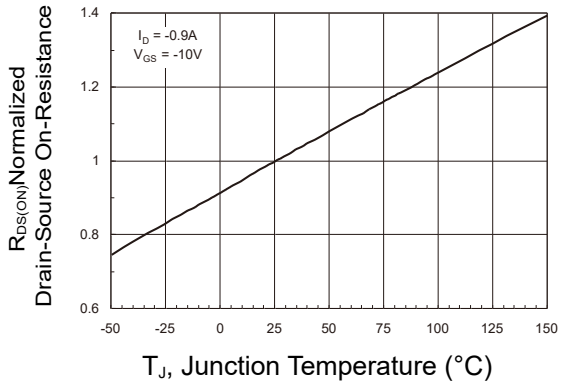


Figure 3: On-Resistance Variation with Temperature.

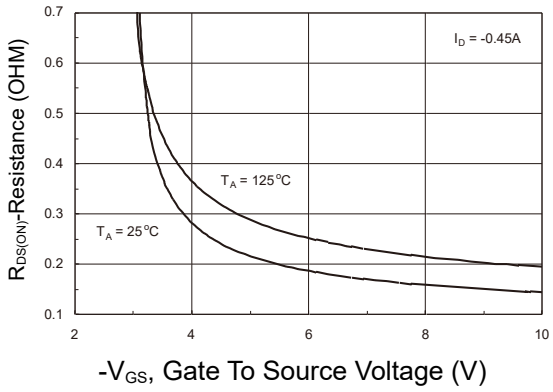


Figure 4: On-Resistance Variation with Gate-to-Source Voltage.

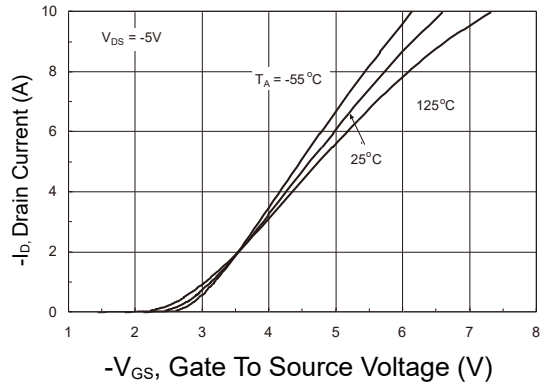


Figure 5: Transfer Characteristics.

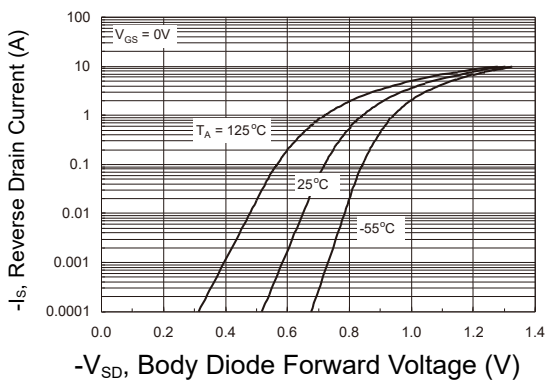


Figure 6: . Body Diode Forward Voltage Variation with Source Current and Temperature.

7.2Typical Characterisitics

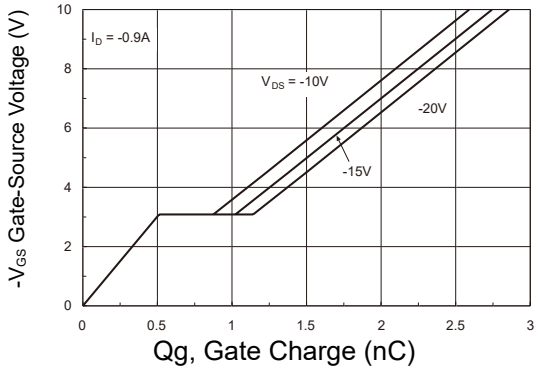


Figure 7: Gate-Charge Characteristics

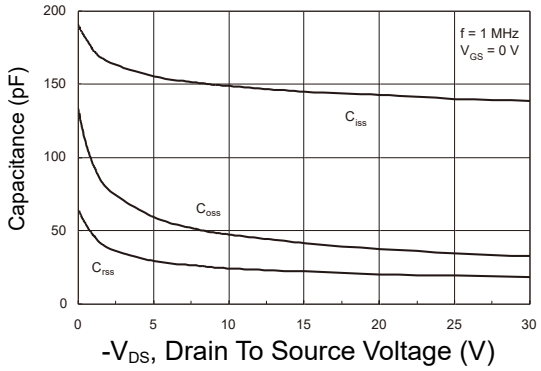


Figure 8: Capacitance Characteristics

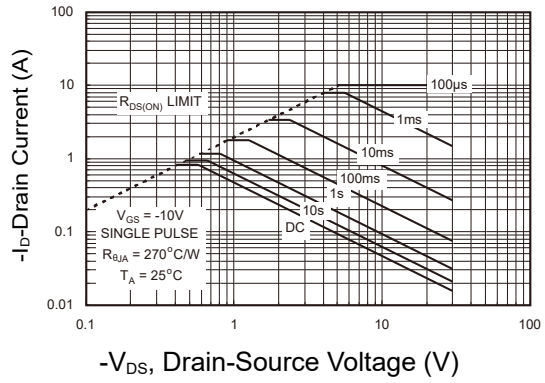


Figure 9: Maximum Safe Operating Area.

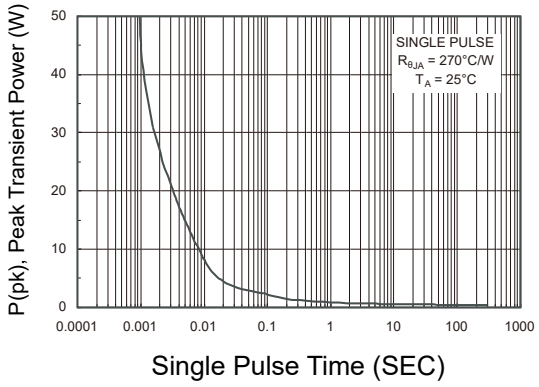


Figure 10: Single Pulse Maximum Power Dissipation.

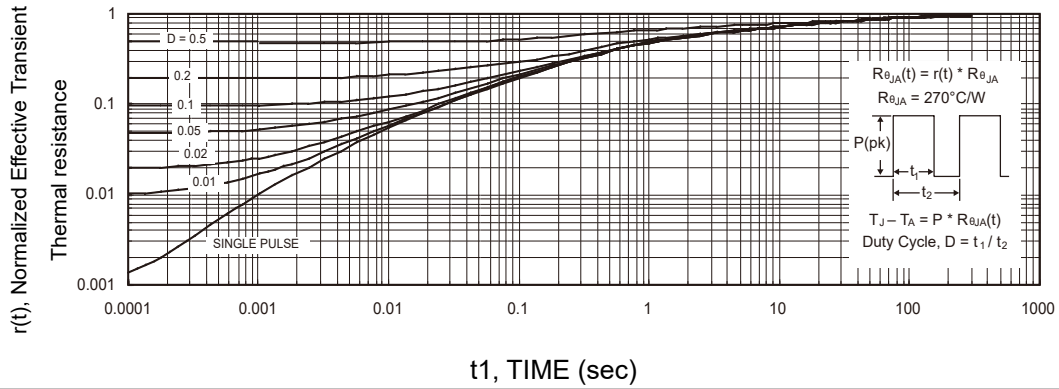
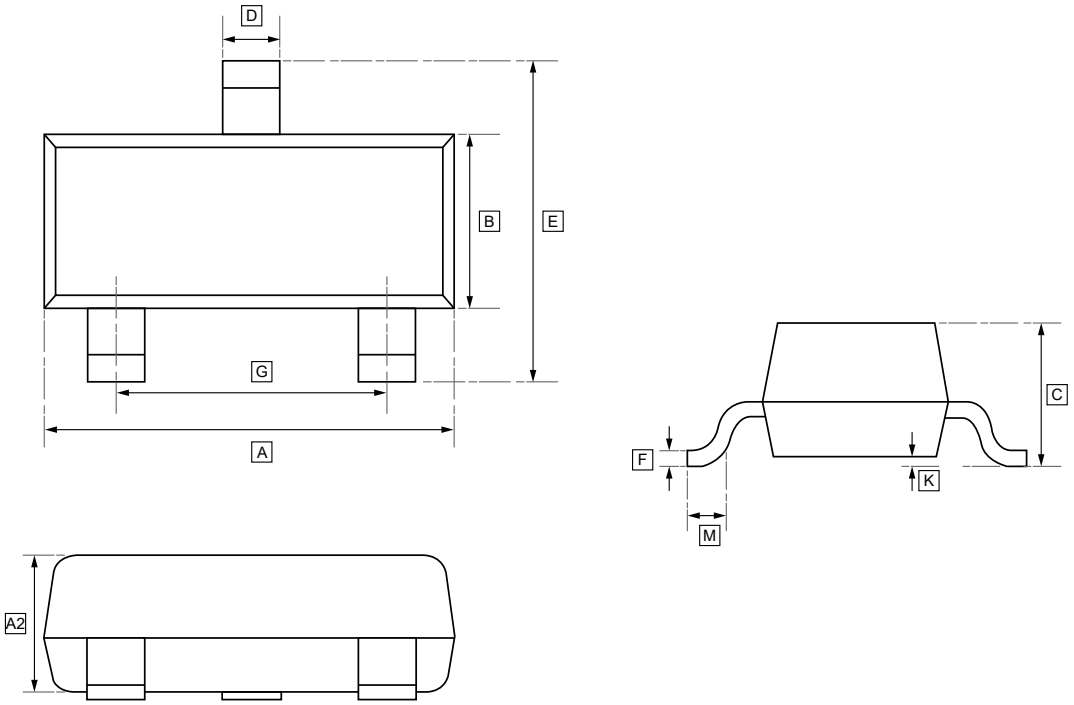


Figure 11. Transient Thermal Response Curve.

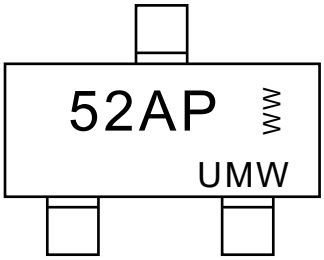
8.SOT-23 Package Outline Dimensions



DIMENSIONS (mm are the original dimensions)

Symbol	A	B	C	D	E	G	K	M	A2	F
Min	2.85	1.20	0.90	0.40	2.25	1.80	0.00	0.30	0.95	0.095
Max	3.04	1.40	1.10	0.50	2.55	2.00	0.10	-	1.05	0.115

9.Ordering information



WW: Batch Code

Order Code	Package	Base QTY	Delivery Mode
UMW FDN352AP	SOT-23	3000	Tape and reel

10.Disclaimer

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